

Description

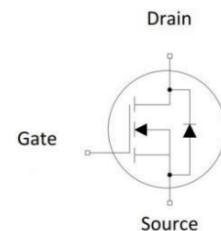
EC65R28E N-channel Multi-Epi Super Junction MOSFETs

Features

650V, 15.0A
Very low FOM RDS(on)×Qg
100% UIS tested
RoHS compliant

Application

Power factor correction (PFC)
Switched mode power supplies (SMPS)
Uninterrupted power supply (UPS)



TO-252

Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	TUBE (PCS)	Inner BOX (PCS)	Per Carton (PCS)
EC65R28E	EC65R28E	TAPING	TO-252	13inch	2500	25000

Absolute Maximum Ratings (T_c=25°C unless otherwise specified)

Symbol	Parameter		Max.	Units
V _{DSS}	Drain-Source Voltage		650	V
V _{GSS}	Gate-Source Voltage		±30	V
I _D	Continuous Drain Current	T _c =25°C	15	A
		T _c =100°C	9	A
I _{DM}	Pulsed Drain Current		45	A
E _{AS}	Single Pulsed Avalanche Energy		320	mJ
P _D	Power Dissipation	T _c =25°C	132	W
R _{θJC}	Thermal Resistance,Junction to Case		0.93	°C/W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C

Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	650	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =650V, V _{GS} =0V	-	-	1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±30V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2.5	-	4.0	V
R _{D(on)}	Static Drain-Sourceon-Resistance	V _{GS} =10V, I _D =7.5A	-	240	280	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =100V, V _{GS} =0V, f=1MHz	-	1126	-	pF
C _{oss}	Output Capacitance		-	41	-	pF
C _{rss}	Reverse Transfer Capacitance		-	2.4	-	pF
Q _g	Total Gate Charge	V _{DD} =520V, I _D =7.5A, V _{GS} =10V	-	26	-	nC
Q _{gs}	Gate-Source Charge		-	3.6	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	10.5	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =400V, I _D =7.5A, R _{GEN} =25Ω	-	20	-	ns
t _r	Turn-on Rise Time		-	40	-	ns
t _{d(off)}	Turn-off Delay Time		-	95	-	ns
t _f	Turn-off Fall Time		-	43	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _F =7.5A	-	0.85	-	V
trr	Body Diode Reverse Recovery Time	V _R =400V I _F =7.5A, dI/dt=100A/μs	-	405	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	4.0	-	uC

Typical Performance Characteristics

Figure 1. Output Characteristics

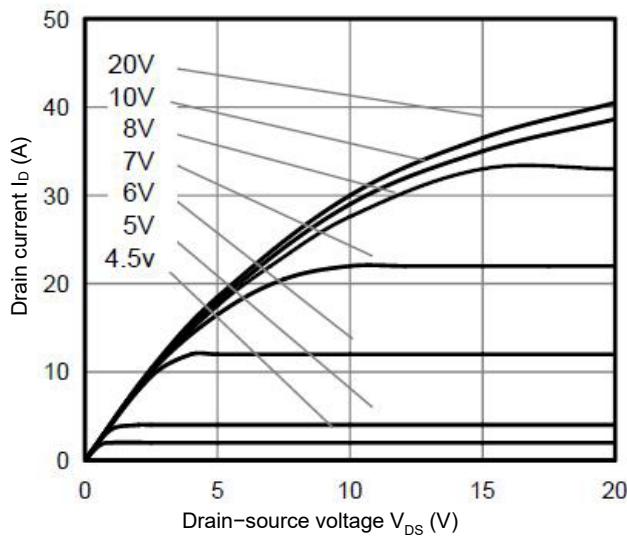


Figure 3. On-Resistance vs. Drain Current

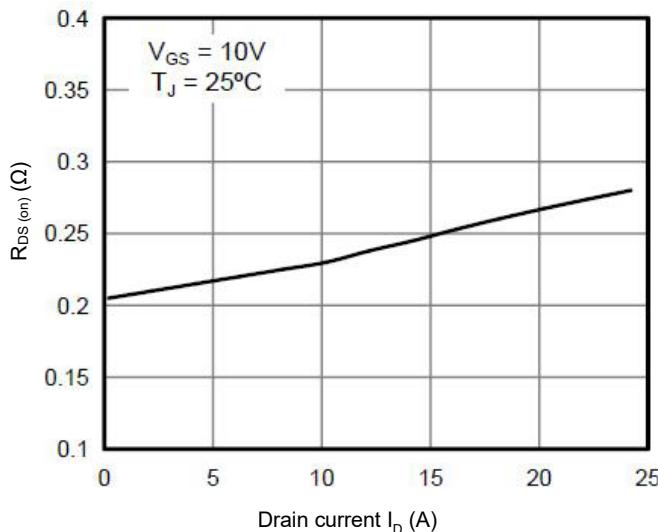


Figure 5. Gate Charge Characteristics

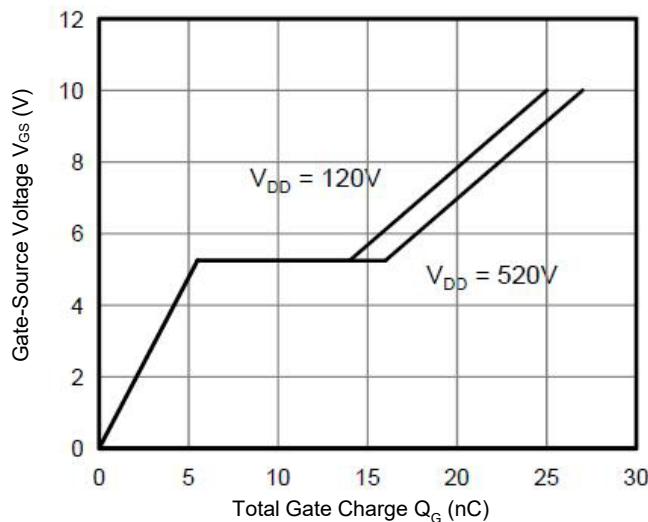


Figure 2. Transfer Characteristics

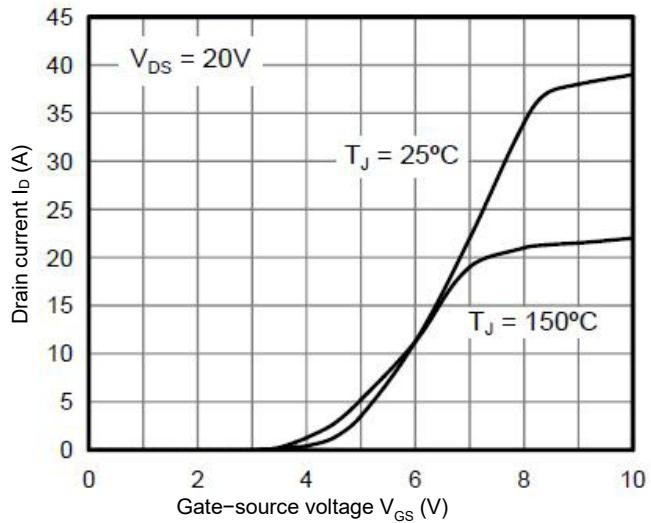


Figure 4. Capacitance Characteristics

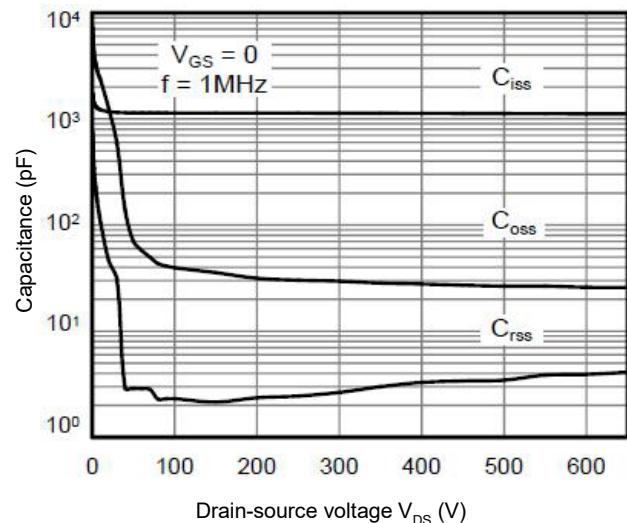


Figure 6. Body Diode Forward Voltage

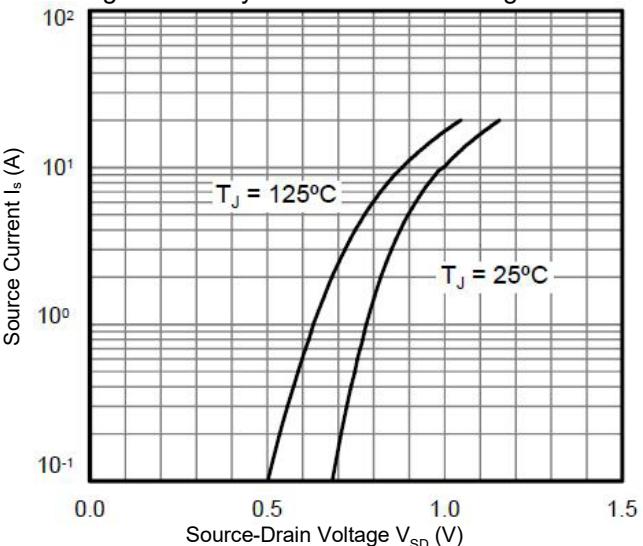


Figure 7. Breakdown Voltage vs. Temperature

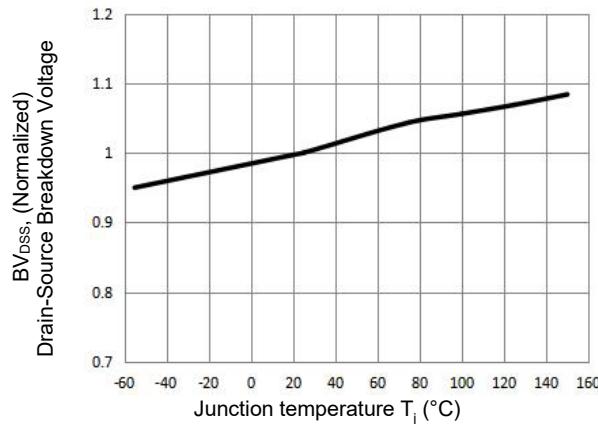


Figure 8. On-Resistance vs. Temperature

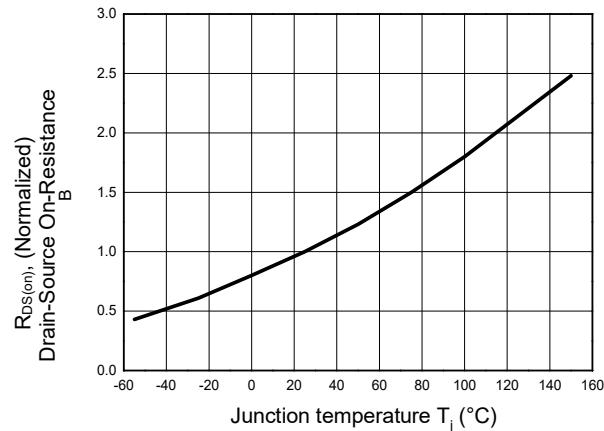


Figure 9. Maximum Safe Operating Area
TO-252/TO-251

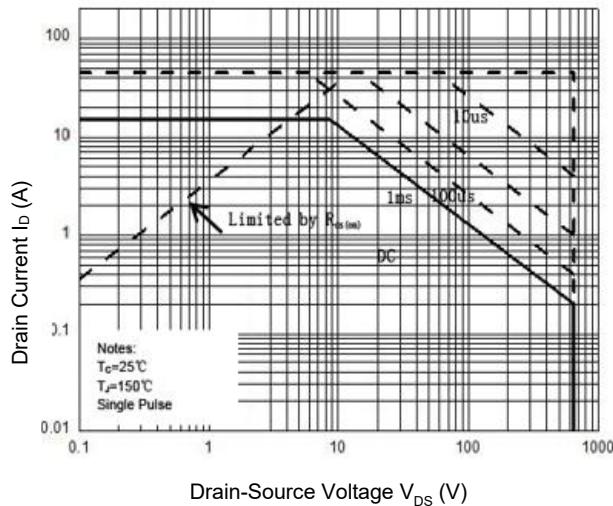
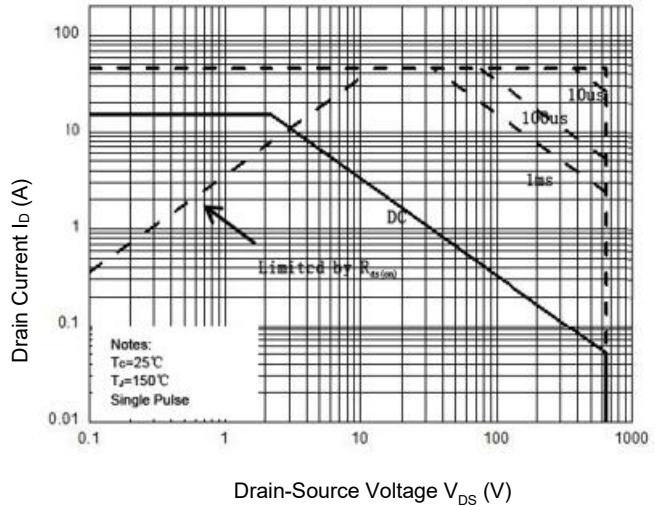
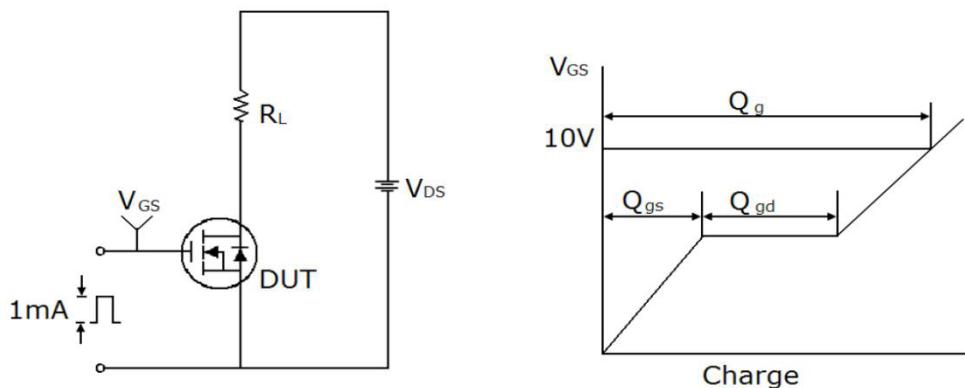


Figure 10. Maximum Safe Operating Area
TO-220F

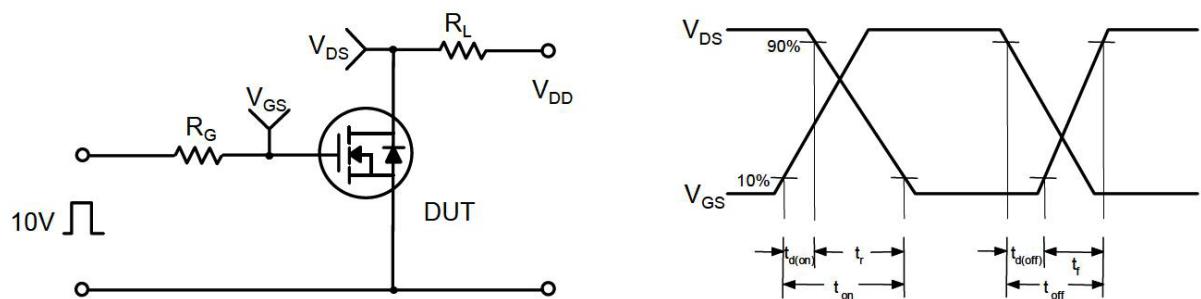


Test Circuit

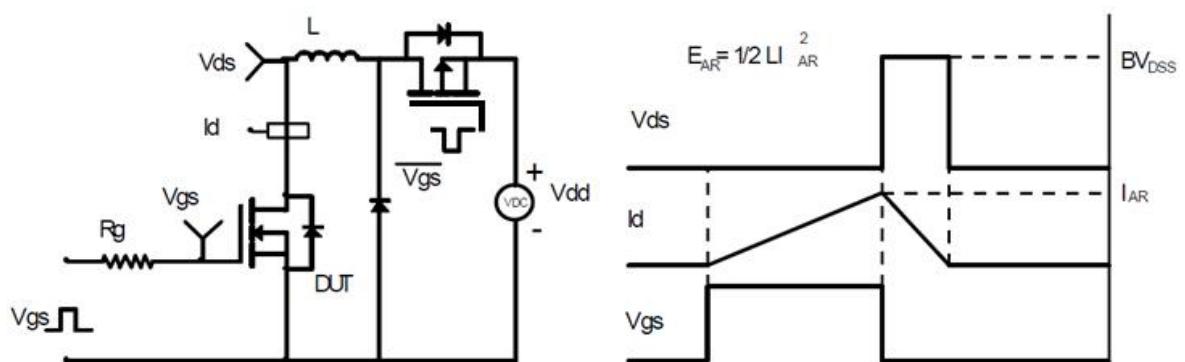
Gate Charge Test Circuit & Waveform



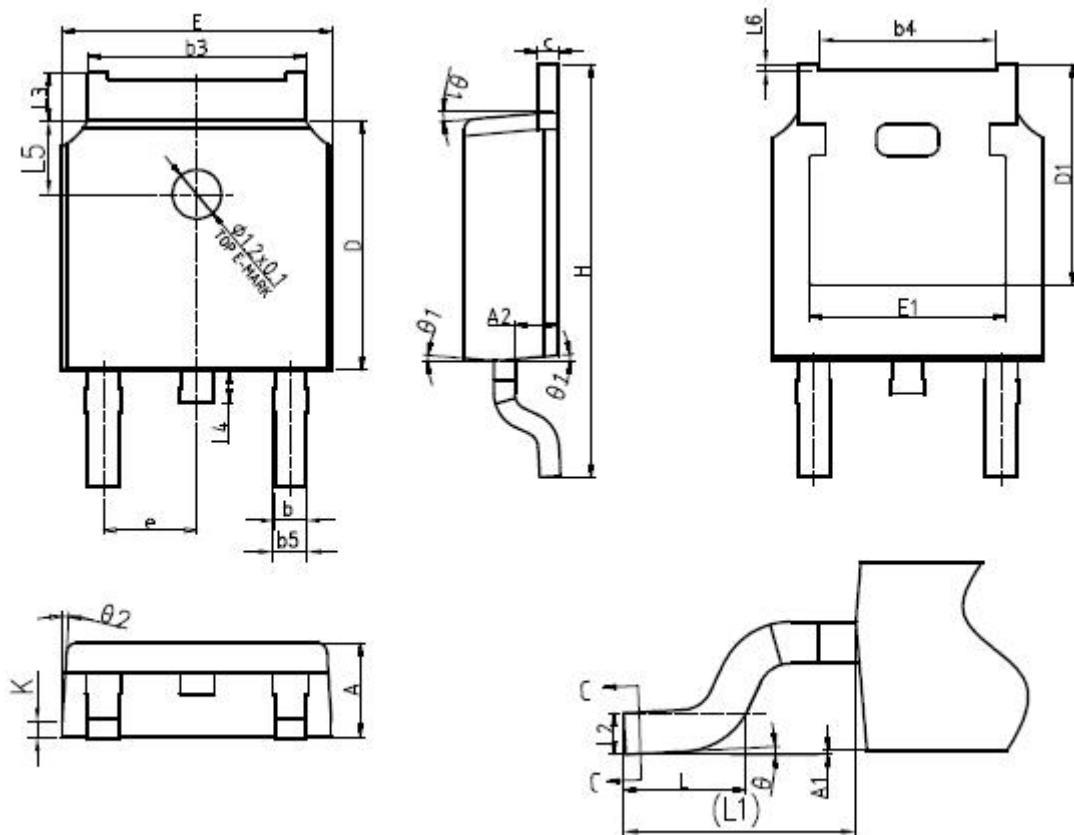
Switching Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveform



Package Mechanical Data-TO-252



单位: mm

SYMBOL	mm		
	MIN	NOM	MAX
*A	2.20	2.30	2.38
*A1	0.00	-	0.10
A2	0.97	1.07	1.17
*b	0.72	0.78	0.85
b1	0.71	0.76	0.81
*b3	5.23	5.33	5.46
b4	4.27	4.32	4.37
b5	0.72	0.88	0.93
*c	0.47	0.53	0.58
c1	0.46	0.51	0.56
*D	6.00	6.10	6.20
D1	5.30REF		

*E	6.50	6.60	6.70
E1	4.70	4.83	4.92
*e	2.286BSC		
L	1.40	1.50	1.70
L1	2.90REF		
L2	0.51BSC		
*L3	0.90	-	1.25
*L4	0.60	0.80	1.00
L5	1.70	1.80	1.90
L6	0	0.047	0.123
θ	0°	-	8°
*θ1	5°	7°	9°
θ2	5°	7°	9°
K	0.40REF		

Product Naming Rules

